

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	611	(discrete WITH (passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 11:53
L2	1	(discrete WITH (passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3 AND ((wirebond\$3 OR wire-bond\$3 OR "wire bond" OR "wire bonding" OR "wire bonded")) WITH (Au OR gold)) AND ((pad OR electrode) WITH (Al OR aluminum)) AND ((plurality OR multiple) WITH (interconnection OR wiring OR lines) WITH level WITH dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 11:57
L3	1	((passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3 AND ((wirebond\$3 OR wire-bond\$3 OR "wire bond" OR "wire bonding" OR "wire bonded")) WITH (Au OR gold)) AND ((pad OR electrode) WITH (Al OR aluminum)) AND ((plurality OR multiple) WITH (interconnection OR wiring OR lines) WITH level WITH dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 11:59
L4	930	((passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:00
L5	888	(capacitor WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:00

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L6	93	(discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:13
L9	1	("6303423").PN.	USPAT	OR	OFF	2006/09/28 12:48
L10	93	(aluminum WITH pad WITH cap) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:49
L11	6	(aluminum WITH pad WITH "metal cap") AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 15:24
L12	27	"gold pad" WITH ("wire bond" OR "wire bonding" OR "wire bonded" OR wirebond\$3 OR wire-bond\$3) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 15:58
L13	1	"second thick metal lines" AND "first thick metal lines" AND interconnection AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 16:00
L14	5	(second OR plurality OR multiple) WITH thick WITH (wiring OR interconnection OR metallization) WITH (post OR above) WITH passivation AND (die OR chip) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 16:05
L15	72	(second OR plurality OR multiple) WITH (wiring OR interconnection OR metallization) WITH (post OR above) WITH passivation AND (die OR chip) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 16:12
L16	2	("6495442").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/28 18:00

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L17	4425	(257/686,685,723).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/28 18:00
S1	137	((MOU-SHIUNG) near2 (LIN)).INV.	US-PGPUB; USPAT	OR	ON	2006/09/26 13:02
S2	33	S1 AND discrete AND capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:28
S3	12	("6184574" "6303423" "6383916" "6495442" "6504236" "6515369").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:30
S4	6	((("5789303") or ("6051489") or ("5789303") or ("6146958"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/22 19:33
S5	3863	(257/723,724).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/22 19:38
S7	1037	S5 AND capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:50
S8	1868	((chip OR die) AND (discrete NEAR\$2 capacitor) AND (wirebond\$3 OR wire-bond\$3 OR wire)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:54

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S9	28	((chip OR die) AND (discrete NEAR\$2 capacitor) AND passivation AND (wirebond\$3 OR wire-bond\$3 OR wire)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:53
S10	28	((chip OR die) AND (discrete NEAR\$2 capacitor) AND passivation AND (wirebond\$3 OR wire-bond\$3 OR wire)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:54
S11	2186	(257/532,535).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/26 13:52
S12	18	(chip OR die OR IC OR "integrated circuit") SAME substrate SAME (interconnect\$4 OR wire OR wiring OR metallization) AND passivation AND ("discrete capacitor" WITH (mount\$3 OR attach\$3 OR solder\$3)) AND (wire-bond\$3 OR "wire bond" OR "wire bonding" OR "wire bonded" OR wirebond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:55
S13	46	("3566203" "4744008" "4945399" "4949163" "4984065" "4994895" "5049979" "5055966" "5119172" "5148265" "5148266" "5281846" "5311057").PN. OR ("5633785").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 14:18
S14	47	("0375154" "4249196" "4288841" "4451845" "4453176" "4453199" "4454529" "4527185" "4567643" "4598307" "4617586" "4636918" "4639826" "4654694" "4680613" "4714952" "4744008" "4749120" "4819056" "4820013" "4851862").PN. OR ("5049979").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:45

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S15	31	("5055907" "5106461" "5212403" "5372967" "5501006" "5576680" "5635767" "5686764" "5884990" "6008102" "6040226").PN. OR ("6303423"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:52
S16	15	("20020135049" "20040183209" "5313693" "5528083" "5633785" "6005778" "6222246" "6222260" "6303423" "6335566" "6373127" "6563192" "6611434" "6670692" "6853087").PN. OR ("7091607"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:54
S17	22	("4598307" "5010445" "5049979" "5115298" "5258329" "5306952" "5457062").PN. OR ("5629240"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:59
S18	68	("4945399" "4989117" "4994936" "5049979" "5103283" "5134539" "5274270" "5311057").PN. OR ("5528083").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:01
S19	47	("5734198" "6054754").PN. OR ("6373127").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:06
S20	33	("4734818" "4744088" "4754366" "4882656" "5034850" "5049979" "5095402" "5272590" "5304506" "5366931" "5498906" "5583739" "5587333" "5606197" "5656834" "5668399" "5701032" "5814892" "5903050").PN. OR ("6222260"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:08
S21	44	("4811082" "5239198" "5528209" "5600257" "5608261" "5629383" "5702984" "5764070" "5772451" "5811868" "5870289" "5903050" "5926359" "5974662" "5977640" "6027980" "6075712").PN. OR ("6222246"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:25

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S22	281	(chip OR die OR IC OR "integrated circuit") SAME (interconnect\$4 OR wire OR wiring OR metallization) AND passivation AND (discrete WITH (mount\$3 OR attach\$3 OR solder\$3)) AND (wire-bond\$3 OR "wire bond" OR "wire bonding" OR "wire bonded" OR wirebond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:56
S23	41	(chip OR die OR IC OR "integrated circuit") SAME (interconnect\$4 OR wire OR wiring OR metallization) AND passivation AND (discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR solder\$3)) AND (wire-bond\$3 OR "wire bond" OR "wire bonding" OR "wire bonded" OR wirebond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 08:23
S24	33	(257/724,728,516,528,532,535,207,203).ccls. AND (discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR connect\$3) WITH (chip OR die OR substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 08:54
S25	46	("3566203" "4744008" "4945399" "4949163" "4984065" "4994895" "5049979" "5055966" "5119172" "5148265" "5148266" "5281846" "5311057").PN. OR ("5633785").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/27 08:38
S26	265	("257" OR "438").clas. AND (discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR connect\$3) WITH (chip OR die OR substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 09:11
S27	6	((("6303423") or ("6515369") or ("6495442") or ("6383916") or ("6184574") or ("6504236")).PN.	USPAT	OR	OFF	2006/09/27 09:13
S28	4	2002-299496 OR 2002-299496	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 09:20

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S29	6	("20020113323" "6624501" "6873038").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 09:36
S30	1	("6921980").PN.	USPAT	OR	OFF	2006/09/27 09:36
S31	27	("20010023993" "20010031548" "20020011656" "20020063340" "20020185721" "20020227753" "20030062629" "20030085466" "20030209806" "5209817" "5407864" "5817541" "5834844" "6002178" "6181569" "6187680" "6200888" "6287893" "6316830" "6350632" "6350633" "6362087" "6365501" "6479900" "6539624" "6590291" "6627824" "6653217").PN. OR ("6921980").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/27 10:36
S32	2	("20040183209").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/28 11:49